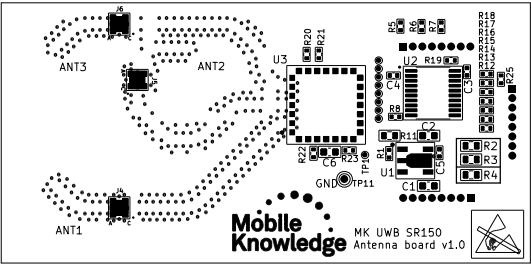


BOARD CHARACTERISTICS

Copper Layer Count:	4	Board Thickness:	1,4640 mm
Board overall dimensions:	70,1000 mm x 34,5000 mm		
Min track/spacing:	0,1500 mm / 0,1500 mm	Min hole diameter:	0,2000 mm
Copper Finish:	ENIG	Impedance Control:	Yes
Castellated pads:	No	Plated Board Edge:	No
Edge card connectors:	No		



Mobile Knowledge MK UWB SR150
Antenna board v1.0

Sheet:
File: SR150_FR4_Protot1_LD0.kicad_pcb

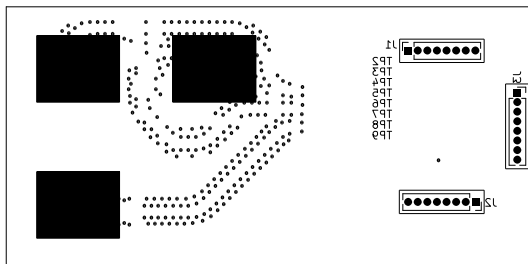
Title: Design 1

Size: A5 Date: 24/03/2022
KiCad E.D.A. kicad (6.0.0)

Rev: v1.0
Id: 1/1

BOARD CHARACTERISTICS

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Mobile Knowledge MK UWB SR150
Antenna board v1.0

Sheet:

File: SR150_FR4_Proto1_LD0.kicad_pcb

Title: Design 1

Size: A5

Date: 24/03/2022

KiCad E.D.A. kicad (6.0.0)

Rev: v1.0

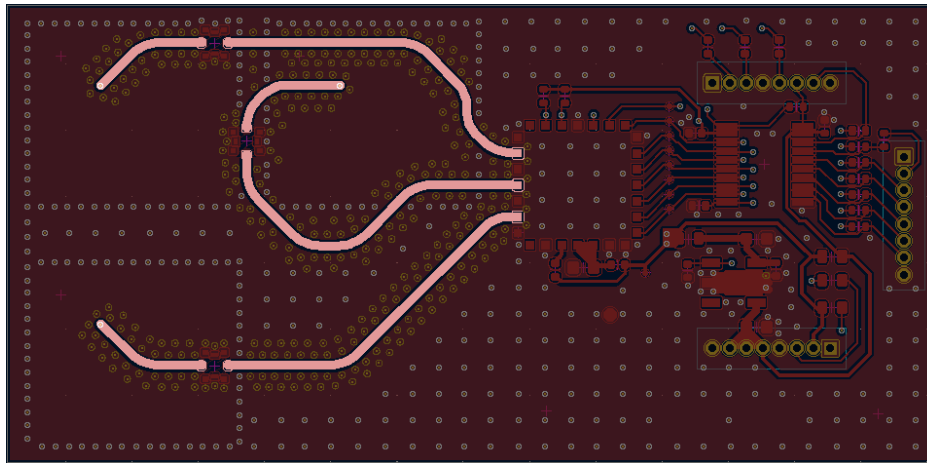
Id: 1/1

Impedance control to highlighted nets (Layers 1-2)

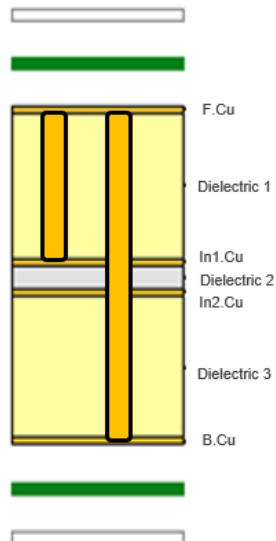
Track characteristics:

- Coplanar wave guide
- Width: 0,67 mm
- Gap to GND: 0,15 mm
- Dielectric height: 0,51 mm

Target impedance 50 Ω \pm 10% tolerance



PCB stack-up:



Layer	Type	Material	Thickness	Color
F.Silkscreen	Top silk screen	-	Not specified	White
F.Paste	Top solder paste	-	Not specified	
F.Mask	Top solder mask	-	Not specified	Green
F.Cu	Copper	-	0,067 mm	
Dielectric 1	Core	FR4 Low Tg IPC 4101/21	0,51 mm	
In1.Cu	Copper	-	0,042 mm	
Dielectric 2	Prepreg	FR4 Low Tg IPC 4101/21	0,22 mm	
In2.Cu	Copper	-	0,035 mm	
Dielectric 3	Core	FR4 Low Tg IPC 4101/21	0,51 mm	
B.Cu	Copper	-	0,06 mm	
B.Mask	Bottom solder mask	-	Not specified	Green
B.Silkscreen	Bottom silk screen	Bottom	Not specified	White

